



Lead-free, no-clean and halide free solder wire

Description:

Interflux[®] **IF 14-22** is a lead-free, no-clean solder wire that contains no rosin nor halides.

IF 14-22 is classified as RE L0 according IPC and EN standards.

IF 14-22 has an increased flux content compared to IF 14-16. It has a larger process window and is suitable for high thermal mass through hole soldering.

The body of the IF 14 flux can almost fully evaporate during soldering (rather than carbonising), leaving a residue that can easily be removed by hand (brush). This results in extremely clean solder joints that are very hard to distinguish from wave or re-flow soldered solder joints.



Products pictured may differ from the product delivered



Key properties

- Non sticky residue, easily removable by hand
- No colophony fumes
- Increased process window
- Absolutely halogen free
- Long tip-life

Availability

Flux type:	IF 14						
Flux content:	2,2% w/w						
		diameters (mm)					
alloy	melting point	0,35	0,50	0,70	1,00	1,50	2,00
Sn96,5Ag3Cu0,5	~217°C	●	●	●	●	●	●
Sn96,5Ag3,5	~221°C	●	●	●	●	●	●
Sn95,5Ag3,8Cu0,7	~217°C	●	●	●	●	●	●
Sn99Ag0,3Cu0,7	~217°C-227°C	●	●	●	●	●	●
Sn99,3Cu0,7	~227°C	●	●	●	●	●	●
Sn99Q ^C (*)	~232°C		●	●	●	●	●

Note: other alloys and diameters upon request ● = available ● = upon request

(*) Sn99Q^C is an alloy designated for reworking LMPA™-Q solder joints





Work Instructions

Manual soldering

The advised working temperature is between 320°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C. The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application. Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered. Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety datasheet of the product.



Test results

Conform EN 61190-1-3(2007), IPC J-STD-004(A) and Bellcore

Property	Result	Method
Chemical		
flux designator	RE L0	J-STD-004
	F-SW 33	DIN 8511
	1.2.3	ISO 9454
qualitative copper mirror	pass	J-STD-004 IPC-TM-650 2.3.32
qualitative halide		
silver chromate (Cl, Br)	pass	J-STD-004 IPC-TM-650 2.3.33
spot test (F)	pass	J-STD-004 IPC-TM-650 2.3.35.1
quantitative halide	0,00%	J-STD-004 IPC-TM-650 2.3.35
Environmental		
SIR test	pass	J-STD-004 IPC-TM-650 2.6.3.3
	pass	TA-NWT-000078 13.1.4
qualitative corrosion, flux	pass	J-STD-004 IPC-TM-650 2.6.15
electro chemical migration	pass	TA-NWT-000078 13.1.5



Packaging

The standard packaging is as follows:

For 0,35mm: spool of 100g

For all other diameters: spool of 500g

Other spool sizes upon request

Trade name : IF14-22 Lead-Free, Halide Free, No-Clean Solder Wire

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